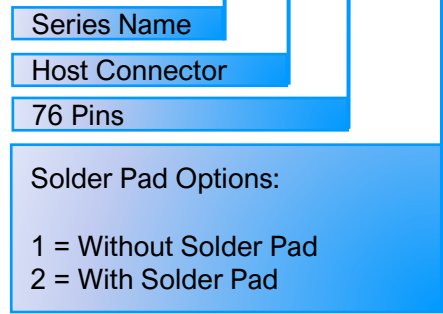


**SPECIFICATIONS:**

- Insulation Resistance: 1,000MΩ min. at 100V DC
- Withstanding Voltage: 300Vrms for 1min
- Voltage Rating: 30V DC
- Current Rating: Contacts:
  - Signal: 0.5A/ pin
  - Power: 1.5A/ pin (Upto 2.25A/pin capability depending on PCB condition)
- Contact Resistance: 10mΩ max. at 20mV max.
- Operating Temp.: -40 - +85°C MAX
- Mating Cycle: 100 times

**PART NUMBER:**

**CN174S-076-000X**



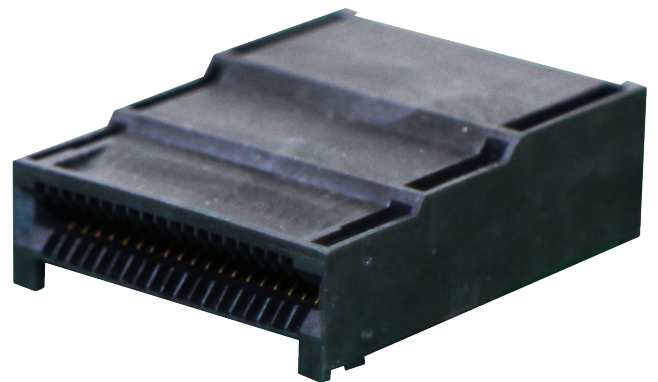
**QSFP-DD MSA COMPLIANT**

**MATERIALS AND FINISH:**

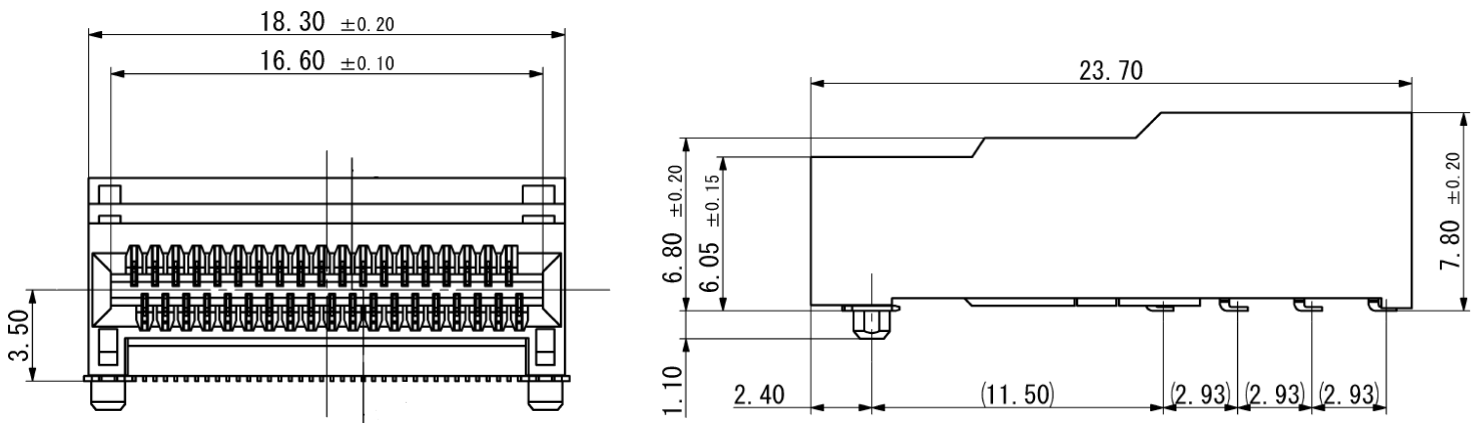
- Blade Contacts: Cu Alloy
- Solder Pad: Cu Alloy
- Insulator & Over mold: LCP

**FEATURES:**

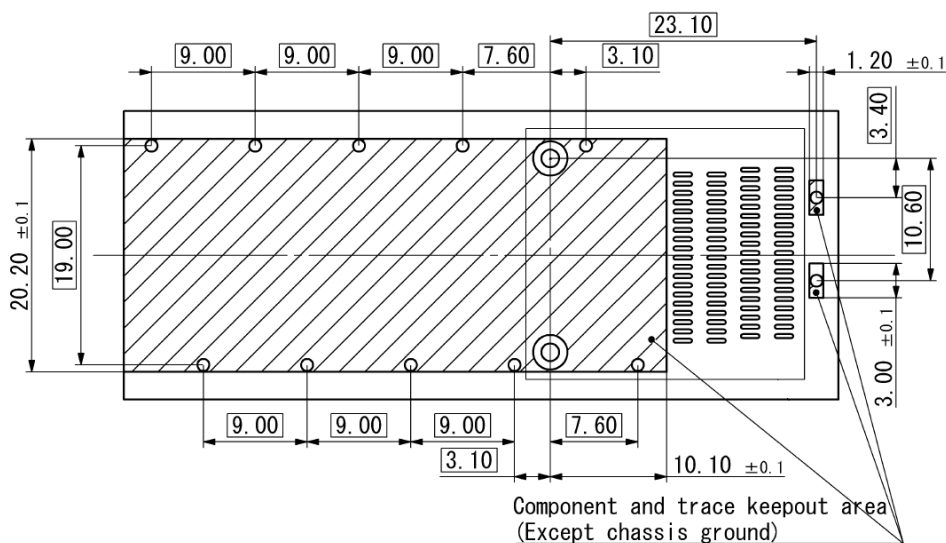
- QSFP-DD MSA Design Guideline Compliant
- Supports signals:
  - 28Gbps-NRZ & 56Gbps-PAM4 for 200G & 400G
  - Next Gen. 112Gbps-PAM4 for 800G



**OUTLINE DIMENSIONS:**

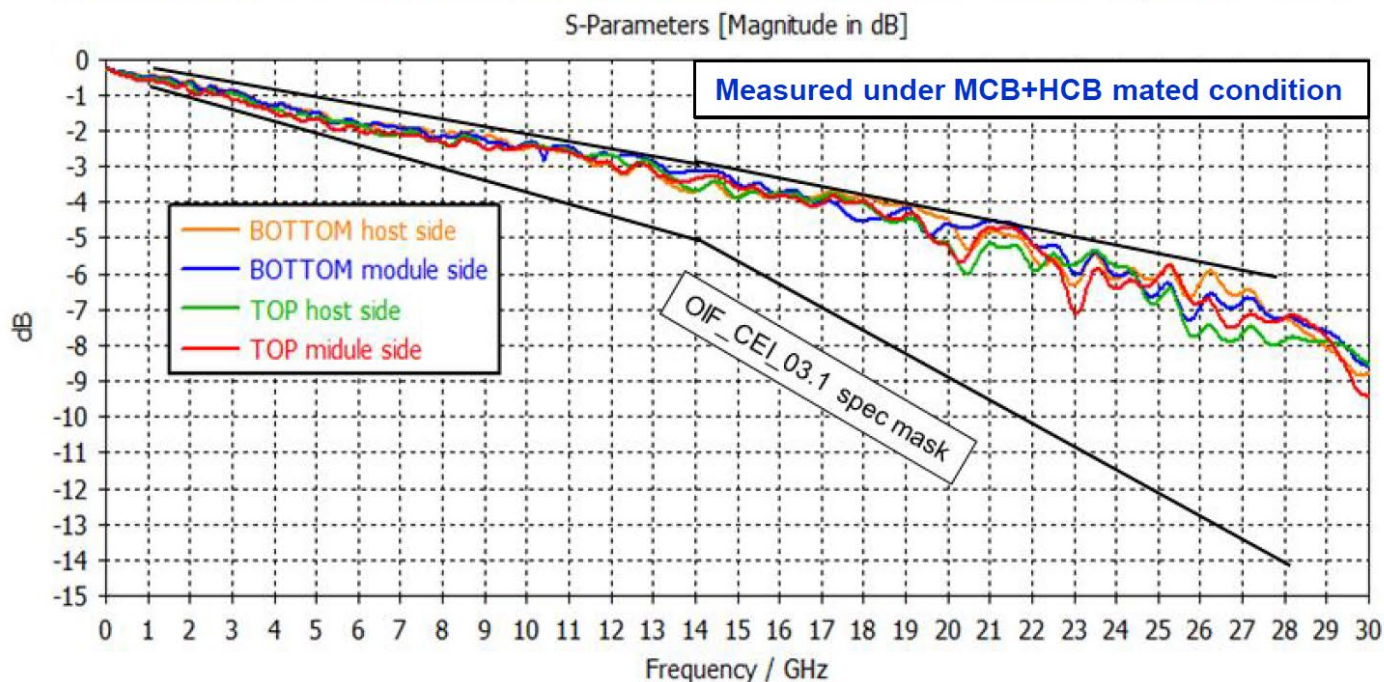


**RECOMMENDED PC BOARD LAYOUT:**

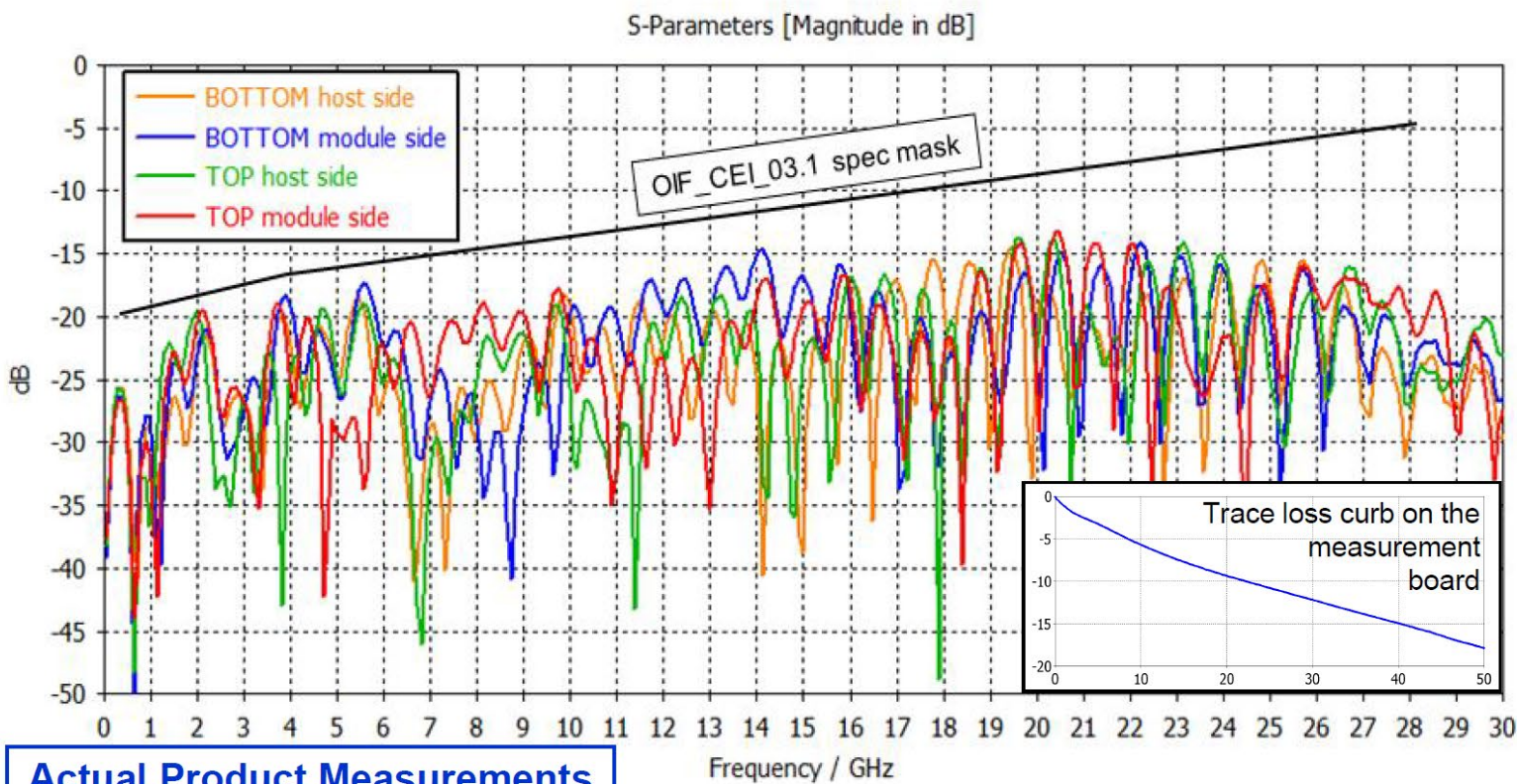


## QSFP-DD Solution

### Insertion Loss Measurements for 1x1 QSFP-DD



### Return Loss Measurements for 1x1 QSFP-DD



#### Actual Product Measurements